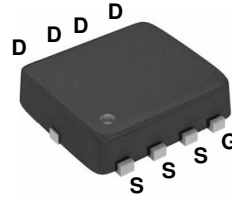
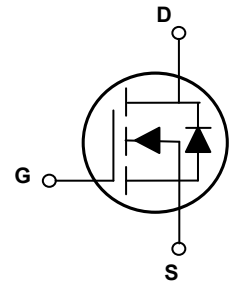


### Main Product Characteristics

$BV_{DSS}$	40V
$R_{DS(ON)}$	9m $\Omega$ (Typ.)
$I_D$	40A



PPAK3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFN4012 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	±20	V
Continuous Drain Current, T <sub>C</sub> =25°C	$I_D$	40	A
Continuous Drain Current, T <sub>C</sub> =100°C		26	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	160	A
Single Pulsed Avalanche Energy <sup>2</sup>	$E_{AS}$	76	mJ
Single Pulsed Avalanche Current <sup>2</sup>	$I_{AS}$	39	A
Power Dissipation, T <sub>C</sub> =25°C	$P_D$	30	W
Power Dissipation-Derate above 25°C		0.24	W/°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	4.17	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	60	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

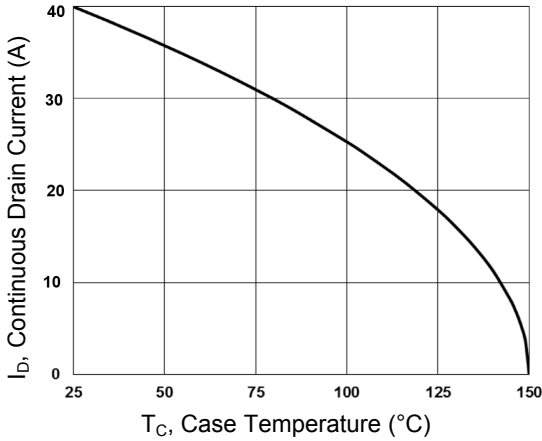
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	-	0.03	-	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V,$ $T_J=25^\circ\text{C}$	-	-	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V,$ $T_J=125^\circ\text{C}$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=10A$	-	9	12	m $\Omega$
		$V_{GS}=4.5V, I_D=5A$	-	12	16	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-5	-	mV/ $^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=3A$	-	16	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=20V, I_D=10A,$ $V_{GS}=4.5V$	-	15.2	-	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.6	-	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	5.9	-	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=15V, R_G=6\Omega,$ $V_{GS}=10V, I_D=1A$	-	12.6	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	2.3	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	64	-	
Fall Time <sup>3,4</sup>	$t_f$		-	5	-	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $F=1\text{MHz}$	-	1460	-	pF
Output Capacitance	$C_{oss}$		-	151	-	
Reverse Transfer Capacitance	$C_{rss}$		-	105	-	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V,$ $F=1\text{MHz}$	-	1.6	2.8	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V,$ Force Current	-	-	40	A
Pulsed Source Current <sup>3</sup>	$I_{SM}$		-	-	160	A
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A,$ $T_J=25^\circ\text{C}$	-	-	1	V

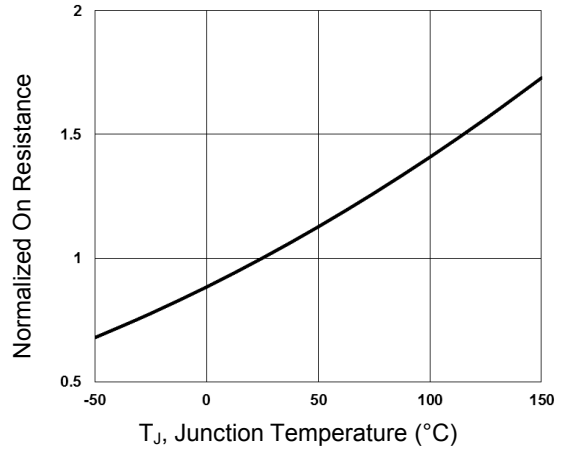
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=39A,$  starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

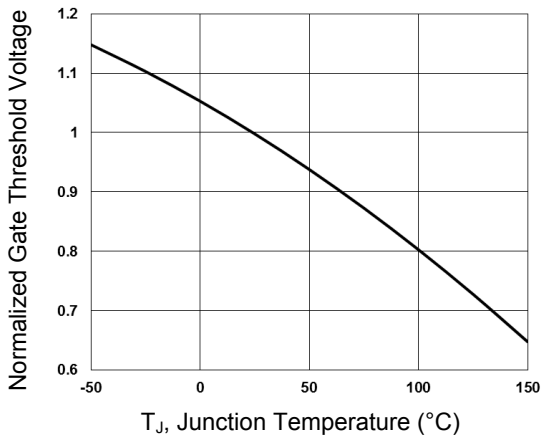
**Typical Electrical and Thermal Characteristic Curves**



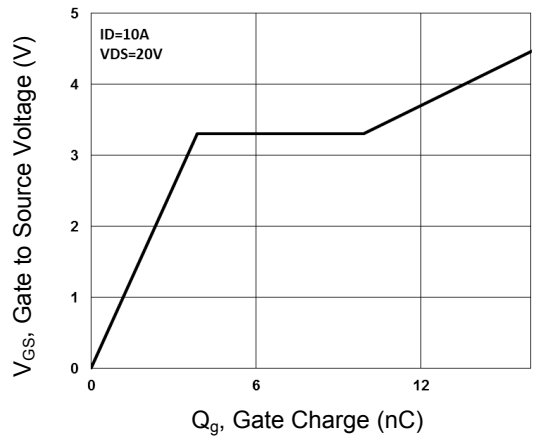
**Figure 1. Continuous Drain Current vs.  $T_c$**



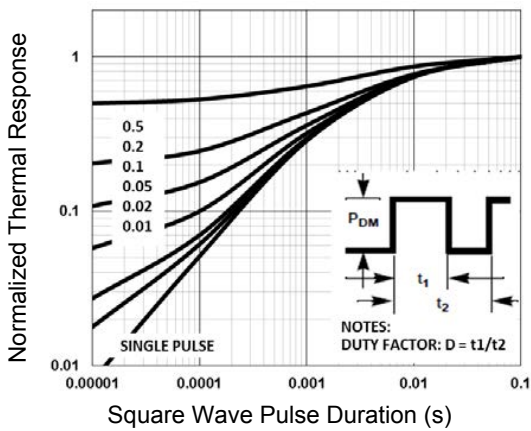
**Figure 2. Normalized  $R_{DS(on)}$  vs.  $T_j$**



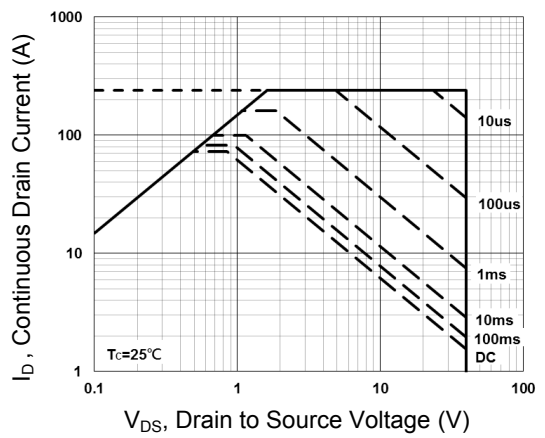
**Figure 3. Normalized  $V_{th}$  vs.  $T_j$**



**Figure 4. Gate Charge Waveform**

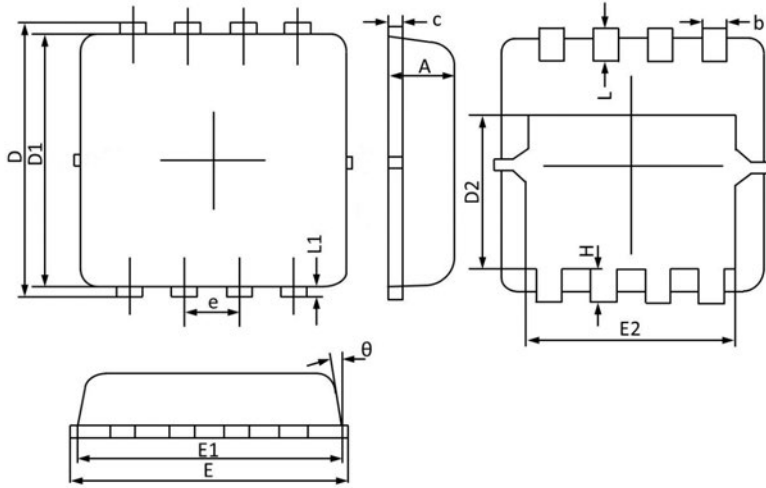


**Figure 5. Normalized Transient Impedance**



**Figure 6. Maximum Safe Operation Area**

### Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.500	0.120	0.138
D1	2.900	3.200	0.114	0.126
D2	1.350	1.950	0.053	0.077
E	3.000	3.400	0.118	0.134
E1	2.900	3.300	0.114	0.130
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.750	0.012	0.030
L	0.300	0.600	0.012	0.024
L1	0.060	0.200	0.002	0.008
θ	6°	14°	6°	14°